

CL04-15 Technical Specifications

FEATURES

- High Overload Surge Capacity
- Durable Epoxy Resin Package



To order with quick disconnect terminals, use the **partnum-TERM**

ABSOLUTE MAXIMUM RATINGS

V _{RRM}	Repeating Peak Reverse Voltage (kV):	15
T_{JMAX}	Max. junction temp.(°C):	130
T _{STG}	Storage temp.(°C):	-40 to +13
Io	Avg. Forward Current (mA):	500
I_{FSM}	Forward Surge Current (A):	40

ELECTRICAL CHARACTERISTICS

I_{R1} Normal temp. Reverse Current (μA)			
@ $V_R = V_{RRM}$, $T_{amb} = 25^{\circ}C$:	5.0 ma		
I_{R2} High temp. Reverse Current (μ A)			
@ $V_R = V_{RRM}, T_{amb} = 100^{\circ}C$:	50 max		
V _F Forward Voltage Drop (V)			
@ I _F =500mA:	13.0		
Reverse Breakdown Voltage (kV)			
@ I _R =100µA:	≥15		
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TEST CONDITIONS

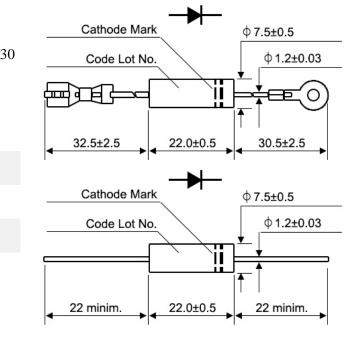
High temp. Reverse Voltage @ 1000 hrs.:

High temp. storage @ 1000 Hrs.: Soldering Resistance Heat Test:

High pressure smoke test @ 10 hrs.: Insulation Resistance Test (1000M Ω): Insulation Strength Test @ 10KV: Lead bend test: Lead pull test:

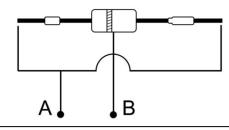
Insulation resistance test condition: Measure between A and B by using a DC 500V Insulation resistance tester

Insulation strength test condition: Apply half sine wave voltage with 10kV wave height between A and B in insulation liquid



 $V_{RM}=V_{RRM}$, f=50Hz, $T_{AMB}=100^{\circ}$ C Half sine voltage with f=50Hz applied, $T_{AMB}=100^{\circ}$ C $T_{AMB}=130\pm2^{\circ}$ C Solder trough temp.: 350±10°C, Dip Time: 3.5s ± 0.5s 120°C, 2 x 10⁵pa Between the center of the body and terminal (*See Fig. 1*) 1 min. between center of the body and terminal. (*Fig.1*) Force 10 N to the lead, bent it to pos. and neg. 90°

Force 70 N of axial to the lead for 1 min.



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